

ICEP2024 Sponsorship Opportunities

2024.4/17 (Wed) ~ 4/20 (Sat)

Venue: Toyama International Conference Center, Toyama, Japan

ICEP (Int'l Conf. on Electronics Packaging) 2024 is looking for Conference Sponsors with various benefits such as publication of your company's logo and advertisement, exhibition of equipment, reception participation, etc. This international conference will cover General Sessions (Advanced Packaging, Design, Modeling and Reliability, Emerging technologies, High-Speed, Wireless & Components, Interconnections, Materials and Processes, Optoelectronics, Power Electronics, Thermal Management), which form the basis of the electronic packaging field. We are also planning sessions on Glass Package and 3D Chiplet, which are attracting attention. Please take advantage of this opportunity, which usually gathers nearly 500 participants from over 10 countries, to promote your company and expand your human network. We look forward to receiving your application!



ENTITLEMENT

		Diamond Sponsor ¥500,000	Platinum Sponsor ¥350,000	Gold Sponsor ¥200,000	Silver Sponsor ¥50,000
Company Logo	Additional Logo recognition 1 ICEP2024 Website, Official Program & Screens during Session breaks	✓	✓	✓	✓
	Additional Logo recognition 2 Registration Website page & platform	✓	✓	—	—
	Additional Logo recognition 3 On Attendee's name badge	✓	—	—	—
Advertisement	Advertising Opportunities 1 Full-page (A4 size 1P) in Final Program & Proceedings	✓	✓	—	—
	Advertising Opportunities 2 Screens during Session breaks PPT1page	✓	✓	—	—
	Advertising Opportunities 3 Pre-recorded movie before a Keynote (1~2min)	✓	—	—	—
	Booth included in sponsorship 4/17(Wed)-19(Fri)	✓	✓	✓	—
	Promotional 1min Speech at Welcome Reception	✓	—	—	—
	Contact Information of Registered Attendees that Opt-In	✓	✓	✓	✓
	Complimentary Registrations (persons)	3	2	1	—
	Limitation of sponsor application (on a FCFS basis)	3	4	18	—

◎ About each benefit:

You can choose whether or not to use each benefit.

After applying, the office will contact you to confirm your application, so please select the benefits you wish to use.

◎ Booth :

- Display panel 1(approx. W: 180cm, H: 210cm) & one table(approx., W:180cm D:60cm) space
- 4/17 – 19 afternoon Break Time: **Coffee break service at Exhibition area**
- 4/18 Evening at booth area: **Sponsors Exhibition Party with all attendees**

◎ Regarding the upper limit on the number of applications:

For each sponsored class, we have set an upper limit on the number of applications as shown in the table. If you are interested, please apply as soon as possible, as it will be on a first-come, first-served basis.

SPONSOR REGISTRATION

Please use online application at sponsorship page of ICEP2024 HP *Before February 28th ,2024
URL : <https://www.jiep.or.jp/icep/sponsor.html>

INQUIRY

Please contact to Secretariat of ICEP2024 (JIEP)

E-mail: icep2024@jiep.or.jp URL: <http://www.jiep.or.jp/icep/>